



### Surface Mount Termination 50 Watts, 50W



#### Description

The RFP-375375A6Z50 is a high performance Alumina (Al<sub>2</sub>O<sub>3</sub>) surface mount termination intended as a lower cost alternative to Aluminum Nitride (AlN) and Beryllium Oxide (BeO). The SMD termination is well suited to all cellular frequency bands such as: AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating 90° hybrids, directional couplers, and for use in isolators.

#### General Specifications

<b>Resistive Element</b>	Thick film
<b>Substrate</b>	Alumina Ceramic
<b>Terminal Finish</b>	Thick film Silver
<b>Operating Temperature</b>	-55 to +125°C (see chart)

Tolerance is ±0.010", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches.

#### Electrical Specifications

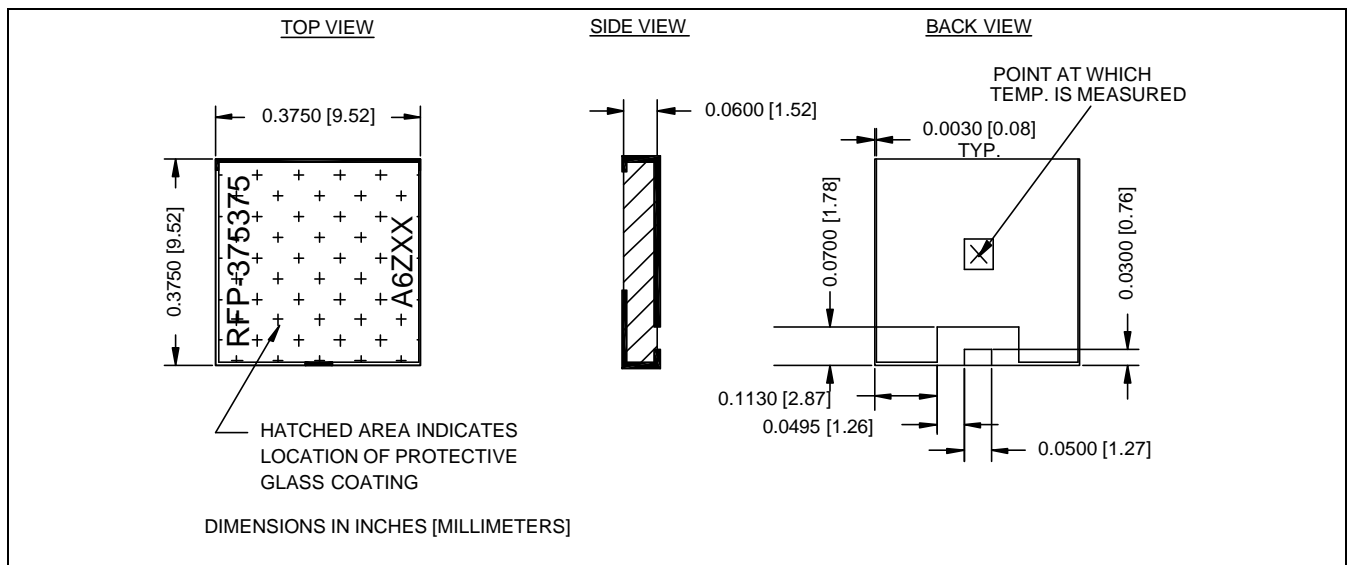
<b>Resistance Value:</b>	50 ohms, ± 2%
<b>Power:</b>	50 Watts
<b>Frequency Range:</b>	1KHz – 2.3GHz
<b>V.S.W.R.:</b>	<1.22:1

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change without notice**

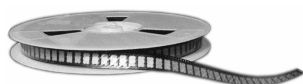
#### Features:

- 50 Watts
- Lowest Cost
- True Surface Mount
- Alumina Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

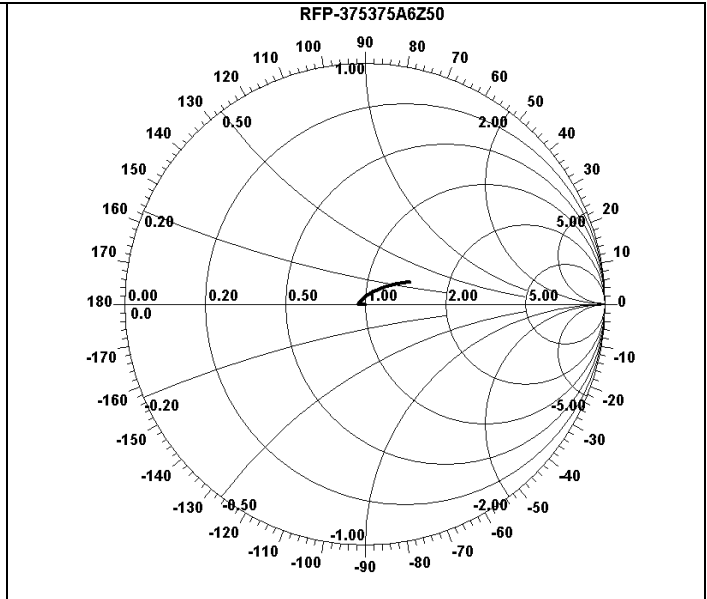
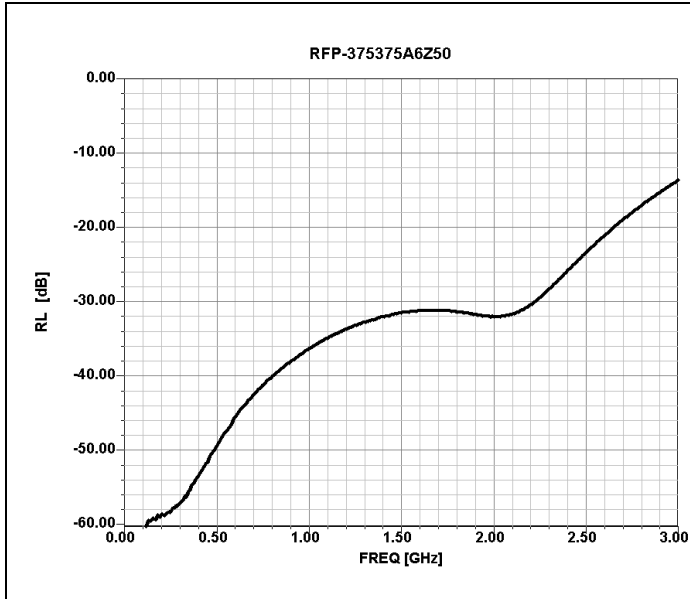
#### Outline Drawing



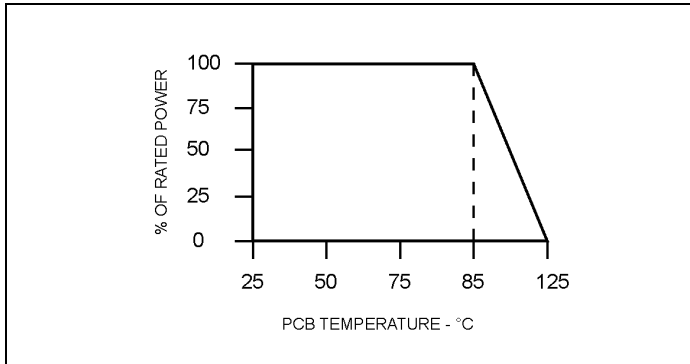
Rev. 11/03/03



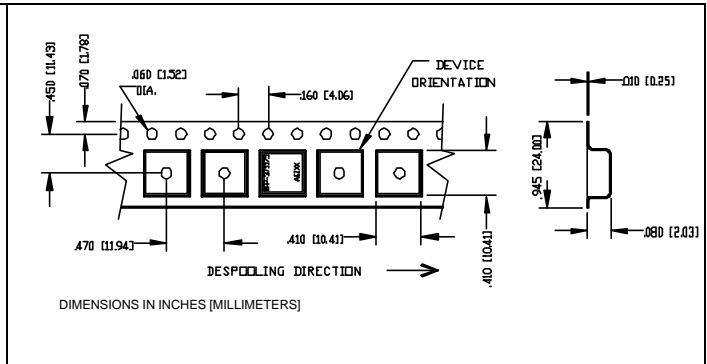
### Typical Performance:



### Power De-rating:



### Tape & Reel:



### Mounting Footprint and Procedure:

Dimension given in inches [millimeters]  
For best thermal performance the PCB should be soldered to the heat sink.

**MOUNTING PROCEDURE**

1. Drill thermal vias through PCB and fill with solder, such as SN63 type.
2. Solder part in place using SN63 type solder with controlled temperature iron (700°F).
3. To ensure good thermal connectivity to heat sink, which is critical for proper operation drill and tap heatsink and mount PCB board to heat sink using screws.

